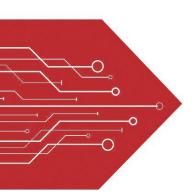
## MSKSEMI















**ESD** 

**TVS** 

**TSS** 

MOV

**GDT** 

**PLED** 

Broduct data speet





#### **Features**

- ◆ 150 Watts peak pulse power (tp = 8/20µs)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- ♦ Working voltages : 5V
- ♦ Protects five I/O lines
- ◆ Low operating and clamping voltages
- ♦ Solid-state silicon avalanche technology

# Applications Notebooks, Desktops, Servers and Video Graphics Cards

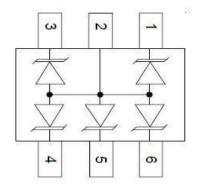
- 1 HOD D
- ◆ USB Power & Data Line Protection
- Monitors and Flat Panel Displays
- ♦ I<sup>2</sup>C Bus Protection
- Portable Instrumentation
- ♦ Set Top Box

## Electrical Characteristics@ Ta=25°Cunless otherwise

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
VRWM	Reverse Working Voltage	Any I/O to Ground			5.0	V
V <sub>BR</sub>	Reverse Breakdown Voltage	IT = 1mA, Any I/O to Ground	6.2			V
lR	Reverse Leakage Current	VRWM = 5V, Any I/O to Ground			1	μΑ
	Clamping Voltage	IPP = 1A, tp =8/20µs, any I/O pin to Ground			10	V
Vc		IPP = 3A, tp =8/20µs, any I/O pin to Ground			15	V
Cı	Junction Capacitance	VR = 0V, f = 1MHz,			10	pF

#### Maximum Rating @ Ta=25°Cunless otherwise specified

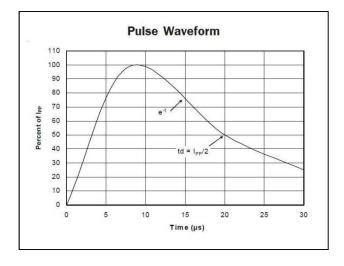
Symbol	Parameter	Ratings	Units
Ррк	Peak Pulse Power (tp = 8/20μs)	150	Watts
TL	Lead Soldering Temperature	260(10sec.)	$^{\circ}$
TJ	T <sub>J</sub> Operating Temperature		$^{\circ}$
T <sub>STG</sub> Storage Temperature		-55 to +150	${\mathfrak C}$

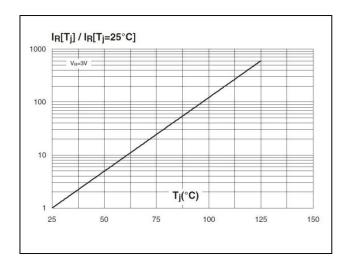


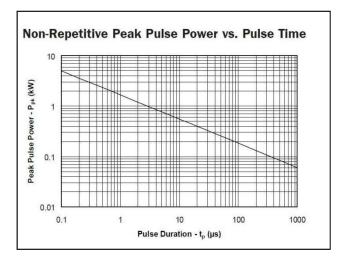
SC-89

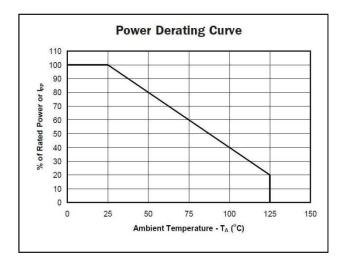


### Typical Characteristics@ Ta=25°Cunless otherwise specified



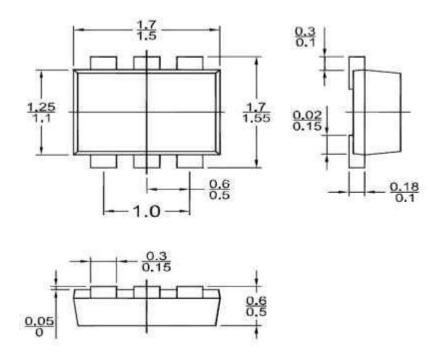




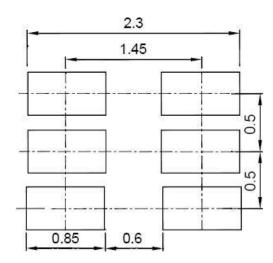




#### **PACKAGE MECHANICAL DATA**



## Soldering Footprint



#### **REEL SPECIFICATION**

P/N	PKG	QTY
PDY0503005-MS	SC-89	3000



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